Number -	19557	contact adj pad	USPAT; US-PGPUB; EPO; JPO;	2002/11/14 10:55
-	0		DERWENT;	
		oxidation adj resistance near4 (contact adj pad)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2001/10/21 13:31
-	7973	oxidation adj resistant	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2001/10/21 13:34
-	3	(oxidation adj resistant) near4 (contact adj pad)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2001/10/21 13:32
-	21288	oxidation adj resistant or oxidation adj resistance	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2001/10/21 13:34
-	134	wire near4 (oxidation adj resistant or oxidation adj resistance)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2001/10/21 13:37
_	17	semiconductor and (wire near4 (oxidation adj resistant or oxidation adj resistance))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2001/10/21 13:38
-	25169	wire adj bonding	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2001/10/21 13:39
-	11	(contact adj pad) and (oxidation adj resistant or oxidation adj resistance) and (wire adj bonding)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2001/10/21 13:42
-	1556	(438/106).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2001/12/12 16:12
_	2	(oxidation adj resistant or oxidation adj resistance) and (("438/106").CCLS.)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2001/10/21 13:44
_	111	gold adj contact adj pad	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2001/10/21 13:45
_	5035	gold adj wire	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2001/10/21 13:45
-	15	(gold adj contact adj pad) and (gold adj wire)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2001/10/21 13:45

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_	64114	semiconductor adj chip	USPAT;	2001/12/12
	04114	semiconductor adj chip	USPAL; US-PGPUB;	16:12
				16:12
			EPO; JPO; DERWENT;	
_	97	(semiconductor adj chip) and	IBM_TDB USPAT;	2001/12/12
		"chip-on-chip"	US-PGPUB;	16:13
		chip-on-chip	EPO; JPO;	16:13
		1	DERWENT;	
1_	188	"chip-on-chip"	IBM_TDB USPAT;	2001/12/12
	100	chip-on-chip	US-PGPUB;	2001/12/12 16:36
			EPO; JPO;	10.30
			DERWENT;	1 1
			IBM TDB	
1_	1112	(257/690).CCLS.	USPAT;	2001/12/12
	1112	(2377030).cclb.	US-PGPUB;	16:45
			EPO; JPO;	10.45
			DERWENT;	
			IBM TDB	
1_	605	(257/777).CCLS.	USPAT;	2001/12/12
1	003	(237) / / / / . CCBS.	US-PGPUB;	16:50
			EPO; JPO;	10.30
			DERWENT;	
			IBM TDB	
_	1023929	wire	USPAT;	2001/12/12
	1023929	MTTC	USPAI; US-PGPUB;	16:51
			EPO; JPO;	16.31
			DERWENT;	
_	368	(("257/777").CCLS.) and wire	IBM_TDB USPAT;	2001/12/12
	300	(( 257/777 ).ccbs.) and wife	US-PGPUB;	16:51
				16:31
			EPO; JPO;	
			DERWENT;	
	5164	connection adj pad	IBM TDB	2001/12/12
<del>-</del>	5164	connection adj pad	USPAT;	
			US-PGPUB;	16:51
			EPO; JPO;	
			DERWENT;	
	30	///!!257/777!!\ CCIC \ and wine\ and	IBM_TDB	2001/12/12
-	30	((("257/777").CCLS.) and wire) and	USPAT;	16:53
		(connection adj pad)	US-PGPUB;	16:53
			EPO; JPO;	]
			DERWENT; IBM TDB	
1_	322387	corrosion or corrode or corroded	USPAT;	2001/12/12
	322367	Collosion of Collode of Colloded	US-PGPUB;	16:54
			EPO; JPO;	10.54
1			DERWENT;	
			IBM TDB	
_	1722415	resistance	USPAT;	2001/12/12
	1,77,417	Testseance	US-PGPUB;	16:54
			EPO; JPO;	10.01
•			DERWENT;	
1			IBM TDB	
_	37	(semiconductor adj chip) and wire and	USPAT;	2001/12/12
		(connection adj pad) and (corrosion or	US-PGPUB;	16:55
	1	connection adj pad) and (corrosion of corrode or corroded) and resistance	EPO; JPO;	10.00
		Collode of Colloded, and leptocance	DERWENT;	
			IBM TDB	
_	2060	   contact adj pad and semiconductor adj	USPAT;	2001/12/12
	2000	chip	US-PGPUB;	17:40
		on p	EPO; JPO;	17.30
			DERWENT;	
	1		IBM TDB	
_	55468	bump or bumps	USPAT;	2002/11/14
	33466	banp or banps	US-PGPUB;	10:56
			EPO; JPO;	10.50
			DERWENT;	
			IBM TDB	
L	L		TDEL TDD	l

	701			1 2001 /10 /10
-	721	(contact adj pad and semiconductor adj chip) and (bump or bumps)	USPAT; US-PGPUB;	2001/12/12 17:41
		crip, and (bump of bumps)	EPO; JPO;	17:41
			DERWENT;	
			IBM TDB	
-	365567	insulative or insualation or dielectric	USPAT;	2001/12/12
			US-PGPUB;	17:42
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	676	"7" and ((contact adj pad and	USPAT;	2001/12/12
		semiconductor adj chip) and (bump or	US-PGPUB;	17:43
		bumps))	EPO; JPO;	
			DERWENT;	Ì
	1722415	unai atauna	IBM_TDB	2001/12/12
-	1722415	resistance	USPAT; US-PGPUB;	2001/12/12 17:43
			EPO; JPO;	17:43
			DERWENT;	
			IBM TDB	
_	342	("7" and ((contact adj pad and	USPAT;	2002/11/14
	","	semiconductor adj chip) and (bump or	US-PGPUB;	10:53
		bumps))) and resistance	EPO; JPO;	
			DERWENT;	
			IBM_TDB	]
_	7	5587337.URPN.	USPAT;	2001/12/12
			US-PGPUB;	17:58
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	/
_	174	(257/694).CCLS.	USPAT;	2001/12/12
			US-PGPUB;	18:08
			EPO; JPO;	
			DERWENT;	
_	276	(257/673).CCLS.	IBM_TDB USPAT;	2001/12/12
1	276	(2577675).0015.	US-PGPUB;	18:12
			EPO; JPO;	10.12
	1		DERWENT;	
			IBM TDB	
	806	(257/686).CCLS.	USPAT;	2001/12/12
			US-PGPUB;	18:36
	ł		EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	İ
-	917	(257/737).CCLS.	USPAT;	2001/12/12
			US-PGPUB;	18:37
			EPO; JPO;	
			DERWENT; IBM TDB	
_	8	5587337.URPN.	USPAT	2002/11/14
		3007337.0KEN.	554111	10:52
_	3335	((flip adj chip or mcm or csp) and	USPAT;	2002/11/14
		(oxidation adj resistant or oxidation	US-PGPUB;	10:55
		resistance) and wire)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	63351	bump or bumps and (contact adj pad and	USPAT;	2002/11/14
		(((flip adj chip or mcm or csp) and	US-PGPUB;	10:56
		(oxidation adj resistant or oxidation	EPO; JPO;	
		resistance) and wire)))	DERWENT;	
	3.55		IBM_TDB	2002/11/14
-	767	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2002/11/14
		mcm or csp) and (oxidation adj resistant	US-PGPUB; EPO; JPO;	10.37
		or oxidation resistance) and wire))	DERWENT;	
			IBM TDB	[
_	1418	(257/690).CCLS.	USPAT;	2003/12/13
	1410	(20.7,050).0000.	US-PGPUB;	09:16
			EPO; JPO;	
	}		DERWENT;	
			IBM TDB	
	* · · · · · · · · · · · · · · · · · · ·	-	<del></del>	· ····

-	197	internal and external and	USPAT;	2003/12/13
		((257/690).CCLS.)	US-PGPUB;	09:18
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1096	(257/777).CCLS.	USPĀT;	2003/12/13
			US-PGPUB;	09:18
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	228	internal and external and	USPAT;	2003/12/13
		((257/777).CCLS.)	US-PGPUB;	09:22
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1096	(257/777).CCLS.	USPAT;	2003/12/13
			US-PGPUB;	09:22
			EPO; JPO;	
	İ		DERWENT;	
			IBM_TDB	